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NO. 353 P. 3

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REPLY UNDER 37 CFR 1.116
EXPEDITED PROCEDURE
TECHNOLOGY CENTER 2800

Docket No.: 524322001200
(PATENT)

I hereby certify that this correspondence is being facsimile transmitted to the Patent and Trademark Office, facsimile no. (571) 273-6300, on the date shown below.
Dated: March 9, 2006 Signature: Valerie Cohen
(Valerie Cohen)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Eitan CADOURI

Application No.: 10/799,061

Confirmation No.: 6747

Filed: March 12, 2004

Art Unit: 2829

For: SELECTING DIE PLACEMENT ON A
SEMICONDUCTOR WAFER TO REDUCE
TEST TIME

Examiner: J. Hollington

AMENDMENT UNDER 37 C.F.R. 1.116

MS AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

This is in response to the Final Office Action dated January 9, 2006 (Paper No. 20060106), for which a response is due on April 9, 2006. Accordingly, this response is timely filed. Additionally, this response is filed within two months of the mailing date of the Final Office Action and therefore qualifies for expedited review. Reconsideration and allowance of the pending claims, as amended, in light of the remarks presented herein are respectfully requested.

*Pls. file
encl
3/23/06*

sf-2068544